

IN THE CLAIMS:

Claims 6 through 8 were previously cancelled. Claims 1 and 5 have been amended herein. All of the pending claims are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

1. (Previously presented) A testing apparatus for a wafer of semiconductor dice comprising:
a first rigid support member for receiving a plurality of semiconductor dice in wafer form having a predetermined orientation, the first rigid support member having a plurality of contact members thereon, the plurality of contact members including a plurality of contact tips including at least one flat contact area for mating with a bump on the wafer, a raised electrical bump or a resilient finger, and having a plurality of electrical connectors connected to the plurality of contact members for establishing communication with test circuitry;
a second support member for selectively engaging the first rigid support member to retain the plurality of semiconductor dice in wafer form therebetween, one of the first rigid support member and the second support member including a single cavity for retaining the plurality of semiconductor dice in wafer form therein during testing;
a single biasing assembly including a single floating platform of a preselected area substantially sized for the single cavity, the single biasing assembly mounted to one of the first rigid support member and the second support member, the single biasing assembly sized for uniformly biasing the plurality of semiconductor dice in wafer form against the plurality of contact members.
2. (Original) The apparatus as claimed in claim 1, wherein the plurality of semiconductor dice comprises a wafer.
3. (Original) The apparatus as claimed in claim 1, wherein the plurality of semiconductor dice comprises a die cluster in wafer form.

4. (Original) The apparatus as claimed in claim 1, wherein the single biasing assembly comprises the single floating platform in contact with an elastomeric polymer member.

5. (Currently amended) The apparatus as claimed in claim 1, further comprising aligning devices for aligning the first rigid support member with the second rigid-support member.

6.-8. (Cancelled)